+44 20 8123 2220
info@marketpublishers.com

Global Semiconductor Packaging Material Market Size study, by Type (Lead frames, Organic substrates, Ceramic packages, Encapsulation resins, Bonding wire, Die attach material, Other) by Application (Consumer electronics equipment, Commercial electronics equipment, Industrial electronics equipment, Others) and Regional Forecasts 2020-2027

https://marketpublishers.com/r/G3465DB577E2EN.html
Date: July 2020
Pages: 200
Price: US$ 4,950.00 (Single User License)
ID: G3465DB577E2EN

Abstracts

Global Semiconductor Packaging Material Market is valued approximately at USD XXX billion in 2019 and is anticipated to grow with a healthy growth rate of more than XX% over the forecast period 2020-2027. A semiconductor package is a casing made of materials such as metal, plastics, glass or ceramic, which contains one or more discrete semiconductor devices or integrated circuits. The packaging facilitates connection of these devices to external environment such as printed circuit boards (PCBs) and also provides protection against threats such as light exposure, mechanical impact and chemical contamination. These materials are critical to semiconductor wafer-level packaging processes, heterogeneous integration, and 3D integration technologies. The market growth is primarily driven by technological advancement and rising adoption of mobile phones and other communication devices. Additionally, rising demand for consumer electronic products is further aiding the growth of market across the world. Moreover, rising number of smart city projects across the globe, and growing trend of miniaturization of electronic products are anticipated to stimulate the market over the forecast period. Hence the growing investments in research for nanotechnology drives the market growth. As per National Nanotechnology Initiative, in US the President's 2018 Budget presented in May 2017, provided USD 1.2 billion for the National Nanotechnology Initiative aimed to support the innovation and research and development in the Nanotechnology. Moreover, this sanction is expected to increase as

+44 20 8123 2220
info@marketpublishers.com

the President’s Budget of 2020 requested USD 1.4 billion for the national Nanotechnology Initiative aiming for continued investment in basic research, early-stage applied research and technology transfer efforts. The cumulative investment in the National Nanotechnology Initiative since its inception in 2001 has amounted to USD 29 billion. In addition, rapid development in electronic industry in emerging countries is further likely to augment the demand for semiconductor packaging material in the near future. As per Indian cellular Association (ICA) the annual production of mobile phones in the country increased to 11 million in 2017 from 3 million in 2014. Which makes the country accountable for 11% of the total global mobile phone production. However, high initial investment requirements and fluctuations in raw material prices are factors which are expected to hamper the market growth over the forecast period of 2020-2027.

The regional analysis of global Semiconductor Packaging Material market is considered for the key regions such as Asia Pacific, North America, Europe, Latin America and Rest of the World. North America is the leading/significant region across the world in terms of market share owing to the growing investments in research and development in Nanotechnology. Whereas, Asia-Pacific is also anticipated to exhibit highest growth rate / CAGR over the forecast period 2020-2027. Factors such as rising demand in consumer electronics and production of semiconductors would create lucrative growth prospects for the Semiconductor Packaging Material market across Asia-Pacific region.

Major market player included in this report are:
Alent Plc
Hitachi Chemical Co. Ltd.
Kyocera Chemical Co. Ltd.
LG Chemical Ltd.
Sumitomo Chemical Co. Ltd.
BASF SE
Mitsui High-Tec Inc.
Henkel Ag & Company
Toray Industries Corporation
Tanaka Holdings Co., Ltd.

The objective of the study is to define market sizes of different segments & countries in recent years and to forecast the values to the coming eight years. The report is designed to incorporate both qualitative and quantitative aspects of the industry within each of the regions and countries involved in the study. Furthermore, the report also caters the detailed information about the crucial aspects such as driving factors & challenges which will define the future growth of the market. Additionally, the report

+44 20 8123 2220
info@marketpublishers.com

shall also incorporate available opportunities in micro markets for stakeholders to invest along with the detailed analysis of competitive landscape and product offerings of key players. The detailed segments and sub-segment of the market are explained below:
By Type:
Lead frames
Organic substrates
Ceramic packages
Encapsulation resins
Bonding wire
Die attach material
Other
by Application:
Consumer electronics equipment
Commercial electronics equipment
Industrial electronics equipment
Others

By Region:
North America
U.S.
Canada
Europe
UK
Germany
France
Spain
Italy
ROE

Asia Pacific
China
India
Japan
Australia
South Korea
RoAPAC
Latin America
Brazil
Mexico

+44 20 8123 2220
info@marketpublishers.com

Rest of the World

Furthermore, years considered for the study are as follows:

Historical year – 2017, 2018
Base year – 2019
Forecast period – 2020 to 2027

Target Audience of the Global Semiconductor Packaging Material Market in Market Study:

Key Consulting Companies & Advisors
Large, medium-sized, and small enterprises
Venture capitalists
Value-Added Resellers (VARs)
Third-party knowledge providers
Investment bankers
Investors

+44 20 8123 2220
info@marketpublishers.com

Contents

+44 20 8123 2220
info@marketpublishers.com

+44 20 8123 2220
info@marketpublishers.com

CHAPTER 7. GLOBAL SEMICONDUCTOR PACKAGING MATERIAL MARKET, REGIONAL ANALYSIS

CHAPTER 8. COMPETITIVE INTELLIGENCE

+44 20 8123 2220
info@marketpublishers.com

CHAPTER 9. RESEARCH PROCESS

+44 20 8123 2220
info@marketpublishers.com

List Of Tables

LIST OF TABLES

+44 20 8123 2220
info@marketpublishers.com

+44 20 8123 2220
info@marketpublishers.com

+44 20 8123 2220
info@marketpublishers.com

List Of Figures

LIST OF FIGURES

+44 20 8123 2220
info@marketpublishers.com

COMPANIES MENTIONED

Alent Plc
Hitachi Chemical Co. Ltd.
Kyocera Chemical Co. Ltd.
LG Chemical Ltd.
Sumitomo Chemical Co. Ltd.
BASF SE
Mitsui High-Tec Inc.
Henkel Ag & Company
Toray Industries Corporation
Tanaka Holdings Co., Ltd.

+44 20 8123 2220
info@marketpublishers.com

I would like to order

Product name: Global Semiconductor Packaging Material Market Size study, by Type (Lead frames, Organic substrates, Ceramic packages, Encapsulation resins, Bonding wire, Die attach material, Other) by Application (Consumer electronics equipment, Commercial electronics equipment, Industrial electronics equipment, Others) and Regional Forecasts 2020-2027

Product link: https://marketpublishers.com/r/G3465DB577E2EN.html

Price: US$ 4,950.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:
info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/G3465DB577E2EN.html